Product / Package Information

Package	MSOP_EP
Body Size	
Lead Count	10
Terminal Finish	100Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.11 E-02	86.20	862000	43.88	438792
Thermosets	Epoxy resin	Proprietary	9.65 E-04	7.50	75000	3.82	38178
Thermosets	Phenol Novolac	9003-35-4	5.15 E-04	4.00	40000	2.04	20362
Other inorganic materials	Antimony Trioxide	1309-64-4	1.93 E-04	1.50	15000	0.76	7636
Thermosets	Brominated Resin	40039-93-8	6.44 E-05	0.50	5000	0.25	2545
Other inorganic materials	Carbon Black	1333-86-4	3.86 E-05	0.30	3000	0.15	1527
Subtotal			1.29 E-02	100	1000000	50.90	509039

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	9.56 E-03	97.57	975706	37.82	378228
Copper & its alloys	Iron	7439-89-6	2.23 E-04	2.28	22789	0.88	8834
Copper & its alloys	Zinc	7440-66-6	1.24 E-05	0.13	1263	0.05	489
Copper & its alloys	Phosphorus	7723-14-0	2.38 E-06	0.02	242	0.01	94
Subtotal			9.80 E-03	100.00	1000000	38.76	387646

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.90 E-05	100.0	1000000	0.39	3916

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	6.83 E-04	100.0	1000000	2.70	27019

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold		3.10 E-04	99.99	1000000	1.23	12260

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon		1.00 E-03	100.0	1000000	3.96	39552

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.16 E-04	80	800000	1.65	16454
Thermosets	Epoxy Resin	Proprietary	7.80 E-05	15	150000	0.31	3085
Others	Curing agent & hardener	Proprietary	2.60 E-05	5	50000	0.10	1028
Subtotal			5.20 E-04	100	1000000	2.06	20567

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.53 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ADI Proprietary